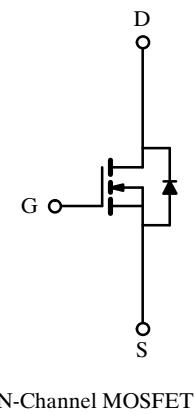
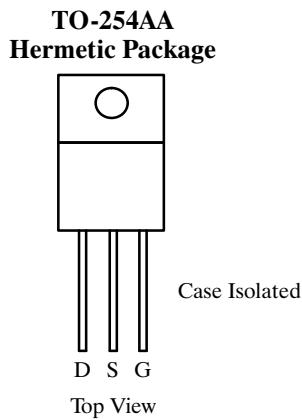


**N-Channel Enhancement-Mode Transistor****Product Summary**

$V_{(BR)DSS}$ (V)	$r_{DS(on)}$ ( $\Omega$ )	$I_D$ (A)
200	0.10	28

**Absolute Maximum Ratings ( $T_C = 25^\circ\text{C}$  Unless Otherwise Noted)**

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	200	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	
Continuous Drain Current ( $T_J = 150^\circ\text{C}$ )	$I_D$	28	A
		18	
Pulsed Drain Current	$I_{DM}$	112	
Maximum Power Dissipation	$P_D$	150	W
		60	
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 to 150	$^\circ\text{C}$
Lead Temperature ( $1/16''$ from case for 10 sec.)	$T_L$	300	

**Thermal Resistance Ratings**

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient	$R_{thJA}$	0.83	50	$^\circ\text{C/W}$
Maximum Junction-to-Case	$R_{thJC}$		0.83	
Case-to-Sink	$R_{thCS}$	0.2		

Specifications ( $T_J = 25^\circ\text{C}$  Unless Otherwise Noted)

Parameter	Symbol	Test Condition	Limit			Unit
			Min	Typ <sup>a</sup>	Max	
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0 \text{ V}, I_D = 250 \mu\text{A}$	200			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250 \mu\text{A}$	2.0		4.0	
Gate-Body Leakage	$I_{\text{GSS}}$	$V_{\text{DS}} = 0 \text{ V}, V_{\text{GS}} = \pm 20 \text{ V}$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 160 \text{ V}, V_{\text{GS}} = 0 \text{ V}$			25	$\mu\text{A}$
		$V_{\text{DS}} = 160 \text{ V}, V_{\text{GS}} = 0 \text{ V}, T_J = 125^\circ\text{C}$			250	
On-State Drain Current <sup>b</sup>	$I_{\text{D}(\text{on})}$	$V_{\text{DS}} = 5 \text{ V}, V_{\text{GS}} = 10 \text{ V}$	28			A
Drain-Source On-State Resistance <sup>b</sup>	$r_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10 \text{ V}, I_D = 18 \text{ A}$		0.080	0.10	$\Omega$
		$V_{\text{GS}} = 10 \text{ V}, I_D = 18 \text{ A}, T_J = 125^\circ\text{C}$		0.15	0.17	
Forward Transconductance <sup>b</sup>	$g_{\text{fs}}$	$V_{\text{DS}} = 15 \text{ V}, I_D = 18 \text{ A}$	9.0	12	27	S
<b>Dynamic</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}} = 0 \text{ V}, V_{\text{DS}} = 25 \text{ V}, f = 1 \text{ MHz}$		2700		pF
Output Capacitance	$C_{\text{oss}}$			850		
Reverse Transfer Capacitance	$C_{\text{rss}}$			300		
Total Gate Charge <sup>c</sup>	$Q_g$	$V_{\text{DS}} = 100 \text{ V}, V_{\text{GS}} = 10 \text{ V}, I_D = 28 \text{ A}$		63	115	nC
Gate-Source Charge <sup>c</sup>	$Q_{\text{gs}}$			14	21	
Gate-Drain Charge <sup>c</sup>	$Q_{\text{gd}}$			32	60	
Turn-On Delay Time <sup>c</sup>	$t_{\text{d}(\text{on})}$			15	35	ns
Rise Time <sup>c</sup>	$t_r$	$V_{\text{DD}} = 100 \text{ V}, R_L = 3.6 \Omega$ $I_D \approx 28 \text{ A}, V_{\text{GEN}} = 10 \text{ V}, R_G = 2.4 \Omega$		100	150	
Turn-Off Delay Time <sup>c</sup>	$t_{\text{d}(\text{off})}$			70	125	
Fall Time <sup>c</sup>	$t_f$			50	100	
<b>Source-Drain Diode Ratings and Characteristics</b>						
Continuous Current	$I_S$				28	A
Pulsed Current	$I_{\text{SM}}$				112	
Diode Forward Voltage <sup>b</sup>	$V_{\text{SD}}$	$I_F = 28 \text{ A}, V_{\text{GS}} = 0 \text{ V}$	0.6		1.8	V
Reverse Recovery Time	$t_{\text{rr}}$	$I_F = 28 \text{ A}, \text{di/dt} = 100 \text{ A}/\mu\text{s}$		175	650	ns
Reverse Recovery Charge	$Q_{\text{rr}}$			0.6		$\mu\text{C}$

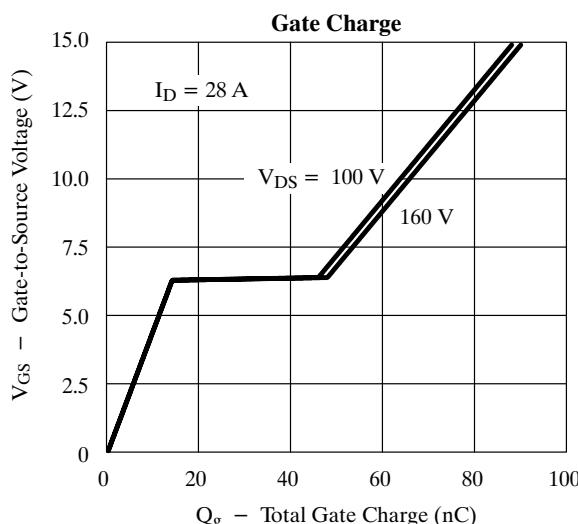
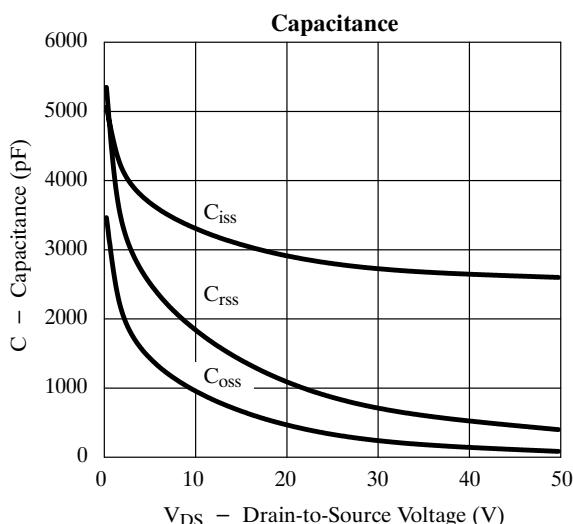
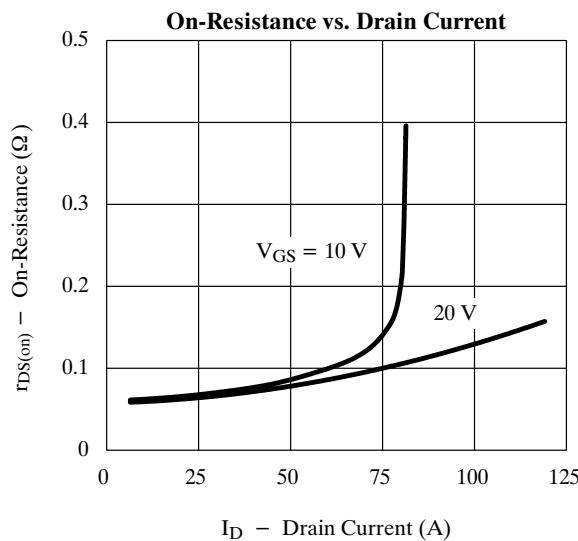
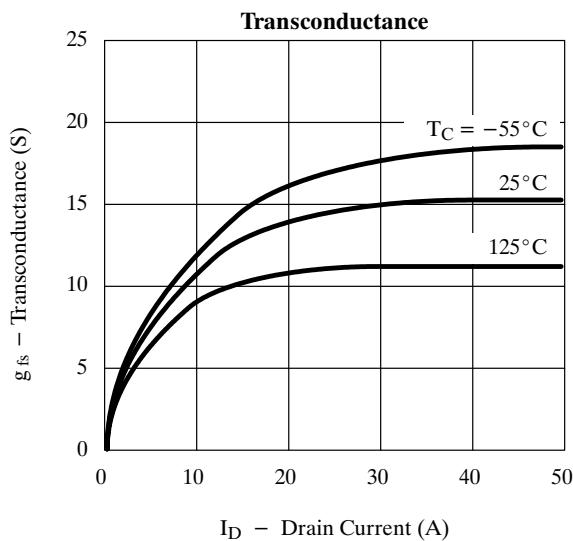
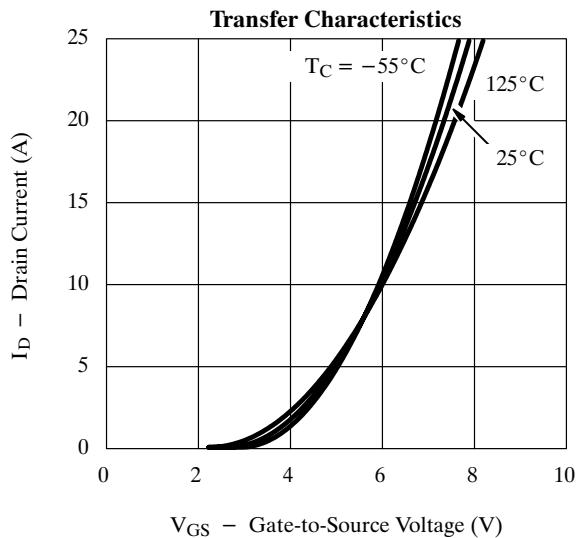
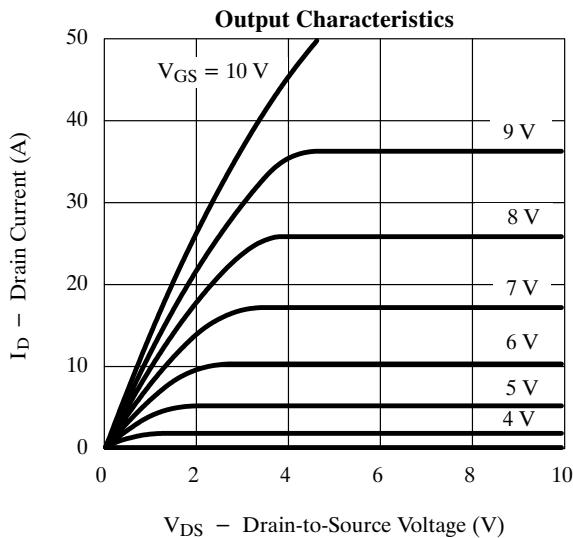
## Notes:

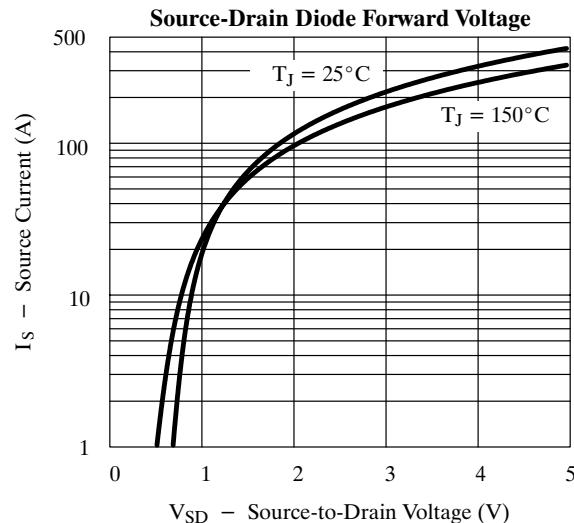
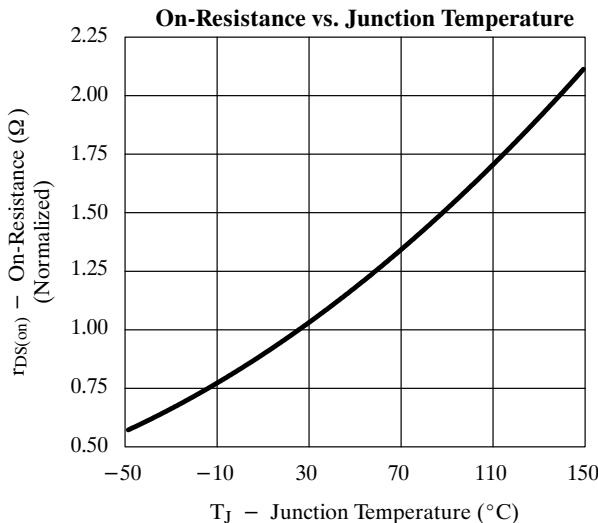
a. For design aid only; not subject to production testing.

b. Pulse test; pulse width duty cycle 2%.

c. Independent of operating temperature.

## Typical Characteristics (25°C Unless Otherwise Noted)



**2N7076****Typical Characteristics (25°C Unless Otherwise Noted)****Thermal Ratings**